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**AUG 17 2005**RESPONSE UNDER 37 CFR 1.116  
EXPEDITED PROCEDURE  
EXAMINING GROUP 2818PATENT APPLICATION  
Docket No.: 8750-045  
Client Ref. No.: SPX200306-0020US

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: In-Ku KANG

Serial No.: 10/632,700 Examiner: Tran, Mai Huong C.

Filed: July 31, 2003 Group Art Unit: 2818

Confirmation No.: 3617

For: MULTI-CHIP MODULE HAVING BONDING WIRES AND  
METHOD OF FABRICATING THE SAMEMail Stop RCE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450**AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR 1.116**

Responsive to the Final Office Action, Paper No. 102005, dated March 22, 2005,  
please amend the application as follows.

**Amendments to the Claims** are reflected in the listing of claims which begins on  
page 2 of this paper.

**Remarks/Arguments** begin on page 7 of this paper.

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